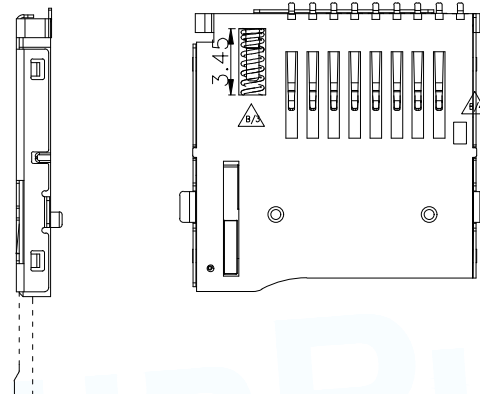
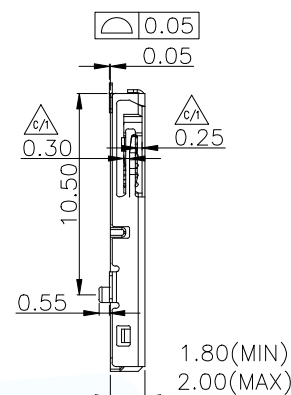
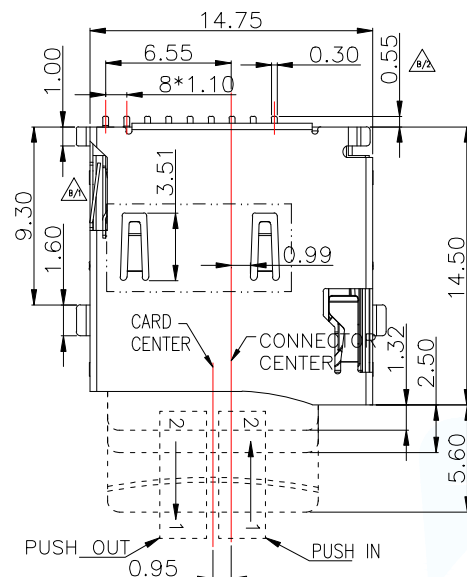
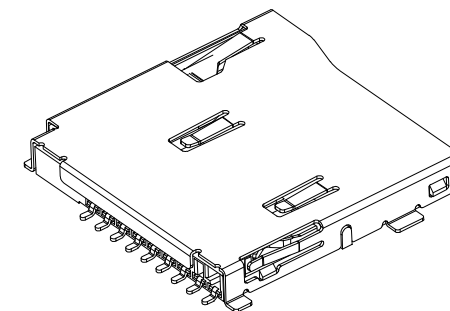


端子镀半金零锡

MAPX	MODIFICATION	DATE	DRAW	APPROVE

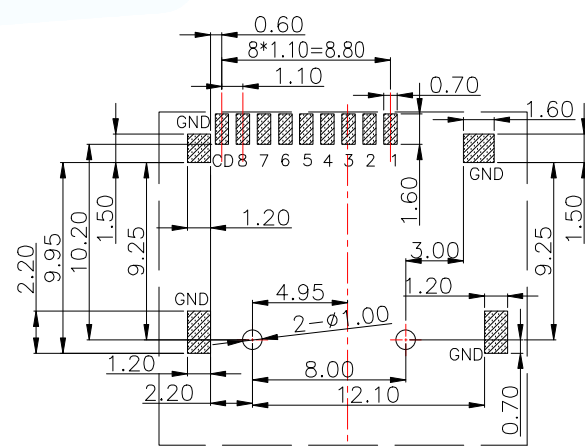
NOTES:

- 1.MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0,COLOR:BLACK.
CONTACT: COPPER ALLOYS.
COVER: COPPER ALLOYS OR STEEL.
- 2.PLATING:
UNDERPLATE: NICKEL.
CONTACT AREA: GOLD OVER NICKEL.
SOLDER AREA: TIN OVER NICKEL.
- 3.MULTIMEDIA CARD COMPATIBLE



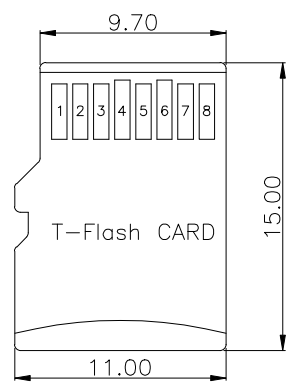
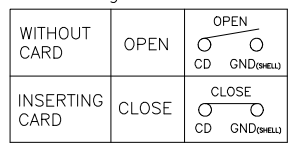
TF CARD PIN DEFINE

PIN NO.	NAME	YYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

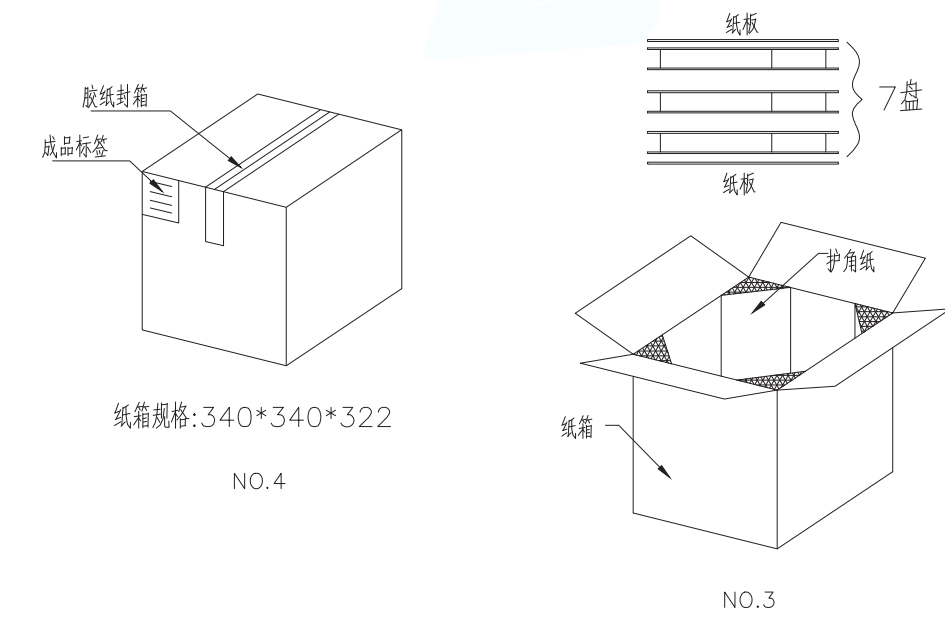
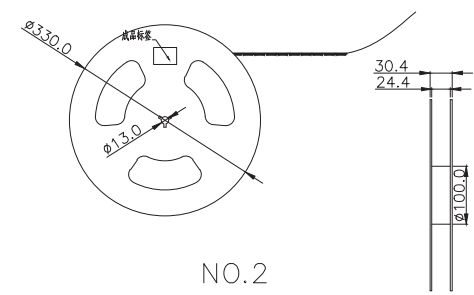
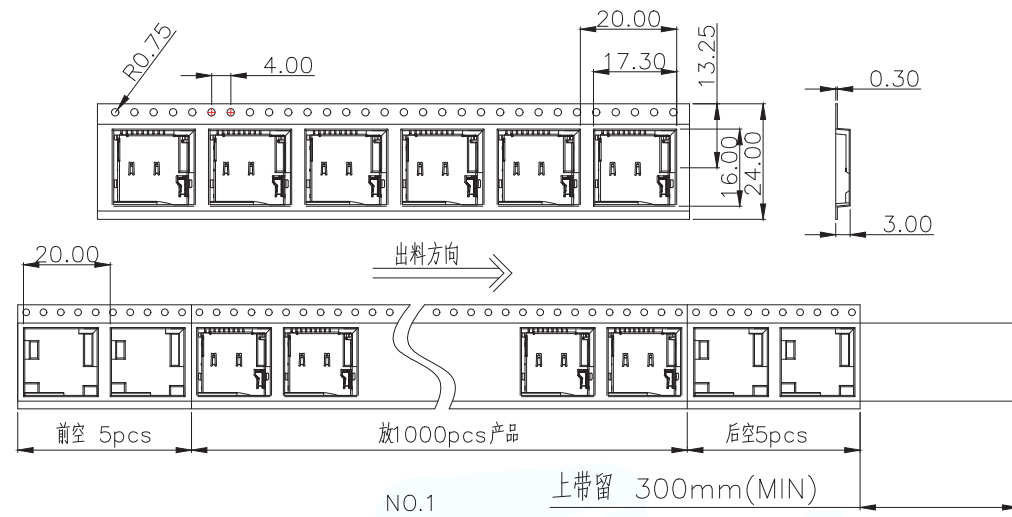


Circuit Diagram for Detect Switch

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



MANUFACTURE DWG			东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MICRO SD CARD PUSH PUSH SMT 不镀金 双压片 外焊	
DECIMALS:	ANGLES:		PAR	TF-115K-BCP9
X.X:±0.35	X.X':±3°		DWN	
X.XX:±0.25	X.XX':±2°		CHKD	
X.XXX:±0.15		APVD		
		CUSTOMER COPY	SCALE1:1	UNIT:MM
			SIZE:A4	UNIT:MM
			SHEET:1F1	REV:A



1. 材质要求:

- 1.1 纸箱的材质为K=K;外形尺寸为34*34*32.2;
- 1.2 卷盘的材质为PS,卷盘的外形尺寸为 $\phi 330 \times 30.4$;

2. 包装方式:

- 2.1 将卷带放入包装机后,前空5PCS,后放产品1000PCS,再后空5PCS;上带留300MM长度。
- 2.2 将包装好的产品从包装机上取下并包装好,贴上内盘标签;
- 2.3 把累叠好的7盘叠放入纸箱中共计7Kset,上下放纸板;
- 2.4 把包装好的成品打包封箱,并在纸箱外贴上标签

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: MICRO SD CARD PUSH PUSH SMT 双压片 外焊 包装图
			PAR TF-115K-BCP9
			DWN
			CHKD
			APVD
DECIMALS:	ANGLES:	SCALE 1:1	UNIT: MM
X.X: ± 0.35	X.X': $\pm 3'$		
X.XX: ± 0.25	X.XX': $\pm 2'$		
X.XXX: ± 0.15			
CUSTOMER COPY		SIZE: A4	SHEET: 2F2
			REV: A